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DIALOG(R)File 351:Derwent WPI

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**Cosmetic material for skin conditioning - contains organic silicone resin**

Patent Assignee: SHINETSU CEHM IND KK (SHIE ); SHISEIDO CO LTD (SHIS )

Number of Countries: 001 Number of Patents: 001

Patent Family:

| Patent No   | Kind | Date     | Applicat No | Kind | Date     | Week     |
|-------------|------|----------|-------------|------|----------|----------|
| JP 62298518 | A    | 19871225 | JP 86143758 | A    | 19860619 | 198806 B |

Priority Applications (No Type Date): JP 86143758 A 19860619

Patent Details:

| Patent No   | Kind | Lan | Pg | Main IPC | Filing Notes |
|-------------|------|-----|----|----------|--------------|
| JP 62298518 | A    |     | 3  |          |              |

Abstract (Basic): JP 62298518 A

Material contains 1-70 wt.% organic silicone resin, 70 mol% or more of which comprises R<sub>3</sub>SiO<sub>1/2</sub> unit (R = hydrocarbon gp. or phenyl gp. of 1-6C) and SiO<sub>2</sub> unit of mol ratio 0.5/1-1.5/1.

USE/ADVANTAGE - The material effectively protects skin (esp. hands) from roughness caused by work using water, for long time. It is smoothly applied, and not washed away easily by washing with water.

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Title Terms: COSMETIC; MATERIAL; SKIN; CONDITION; CONTAIN; ORGANIC; SILICONE; RESIN

Derwent Class: A26; A96; D21

International Patent Class (Additional): A61K-007/48

File Segment: CPI